





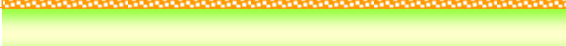













Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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08 163 FR4 55 L10.70 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

08_163_FR4_55_L10.70_p10

Layers	in μ	Material	Build-Up	Assembly		
Layer-1	55 μ	Copper		} A1		
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)	
	100 μ	Prepreg				
Layer-2	70 μ	Copper			} A2	
	100 μ	L-FR4				
Layer-3	70 μ	Copper				
	100 μ	Prepreg				
Layer-4	100 μ	Prepreg				
	70 μ	Copper				
	100 μ	L-FR4				
Layer-5	70 μ	Copper				
	100 μ	Prepreg				
Layer-6	100 μ	Prepreg			} A3	
	70 μ	Copper				
	100 μ	L-FR4				
Layer-7	70 μ	Copper				
	100 μ	Prepreg				
Layer-99	100 μ	Prepreg				
	55 μ	Copper				
						

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